Title: HEAT DISSIPATING DEVICE WITH PRESELECTED DESIGNED INTERFACE FOR THERMAL INTERFACE MATERIALS

Assignee: Intel Corporation

REMARKS

This responds to the Office Action mailed on September 11, 2006.

Claims 1 and 26 are amended and claims 28-29 are canceled. Claims 1-27 are now pending in this application.

§112 Rejection of the Claims

Claims 1-2 and 8-10 were rejected under 35 USC § 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

Applicants amended claim 1, "wherein all of the at least two different metals contact [the outer surface] a thermal interface material..."

The amended claim 1 is supported by the specification on page 3, lines 25-29. Thus, Applicants traverse the §112 rejection to claim 1. Claims 2 and 8-10 depend on claim 1, thus for the same reason as discussed for claim 1, Applicants traverse the §112 rejections to claims 2 and 8-10.

Applicants respectfully request the examiner to withdraw the §112 rejections to claims 1-2 and 8-10.

§102 Rejection of the Claims

Claims 1-2, 8-10, 26, and 28-29 were rejected under 35 USC § 102(e) as being anticipated by Vrtis.

To sustain an anticipation rejection under 35 USC § 102(e), each and every element in a rejected claim must be taught or suggested in the cited reference.

Applicants amended claim 1 as follows:

1. A heat dissipating device, comprising: a main body having an outer surface that is plated or coated with at least two different metals_wherein all of the at least two different metals contact [the outer surface] a thermal interface material to form a design effective for bonding to solder and for adhering to polymer in [a] the thermal interface material, and the outer surface defines serrations around the design.

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Vrtis does not teach or suggest that the outer surface of the main body of the heat dissipating device defines serrations around the design, which is positively recited in the amended claim 1. Thus, Vrtis does not anticipate the amended claim 1.

Claims 2 and 8-10 are, directly or indirectly, dependent on claim 1. Thus, for at least the reasons discussed for claim 1, Vrtis does not anticipate claims 2 and 8-10.

Applicants amended claim 26 as follows:

26. An electronic system, comprising:

an electronic assembly comprising a heat dissipating device, comprising:

a main body having a surface that is plated or coated with at least two different metals to form a design effective for bonding to solder and for adhering to polymer in a polymer solder hybrid, and the surface of the main body defines serrations around the design.

Vrtis does not teach or suggest that the surface of the main body defines serrations around the design, which is positively recited in the amended claim 26. Thus, Vrtis does not anticipate the amended claim 26.

Applicants canceled claims 28 and 29 without prejudice.

Therefore, Applicants respectfully request the examiner to withdraw the rejections to claims 1-2, 8-10, and 26, as well as claims 2 and 8-10 under 35 USC § 102(e), and to allow them.

§103 Rejection of the Claims

Claims 6-7 were rejected under 35 USC § 103(a) as being unpatentable over Vrtis in view of Jech et al.

To sustain a 35 USC § 103(a) rejection, each element of a rejected claim must be disclosed in the proposed combination of the cited documents as set forth in the Office Action.

Claims 6-7 are dependent on claim 1. Claim 6 further recites that the design comprises corner squares. Claim 7 further recites that design comprises a central square.

First, the examiner acknowledges that Vrtis does not go into detail regarding the pattern used to "mask off" areas of the copper substrate which are not to be coated and those which are.

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Furthermore, Jech et al does not disclose the specific design which is positively recited in claim 6.

Moreover, neither Vrtis nor Jech et al teaches or suggests that the outer surface of the main body of the heat dissipating device defines serrations around the design. Such feature is positively recited in the amended claim 1, thus is a feature of both claims 6 and 7.

Therefore, Applicants submit that, even if combined, Vrtis and Jech et al do not teach each of the features recited in claims 6 and 7.

Thus, Applicants respectfully request the examiner to withdraw the rejections to claims 6 and 7 under 35 USC § 103(a) and to allow claims 6 and 7.

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Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney ((612) 373-6976) to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

ASHAY A. DANI ET AL.

By their Representatives, SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. Attorneys for Intel Corporation P.O. Box 2938 Minneapolis, Minnesota 55402 (612) 373-6976

Date the Draw of By Cambridge Janal M. Kalis
Reg. No. 37,650

<u>CERTIFICATE UNDER 37 CFR 1.8:</u> The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexendria, VA 22313-1450 on this 11th day of <u>December</u> 2006.

Amy moriarty

Name

Signature